Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/09/2022

### Details for "SN74AHCT14NSR"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74AHCT14NSR	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	NS   14	5.3x10.3x1.95	224.1

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

#### **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

### **Component Information**

				Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Bond Wire								
Copper and Its Alloys	Copper	7440-50-8	0.096252	99.998961	999990	0.042951	430	
Precious Metals	Silver	7440-22-4	0.000001	0.001039	10	0	0	
Sub-Total			0.096253	100	1000000	0.042951	430	
Die Attach Adhesive								
Precious Metals	Silver	7440-22-4	0.122973	80.00013	800001	0.054875	549	
Thermoplastics	Epoxy	85954-11-6	0.030743	19.99987	199999	0.013719	137	
Sub-Total			0.153716	100	1000000	0.068593	686	
Lead Frame								
Copper and Its Alloys	Copper	7440-50-8	37.664505	97.425	974250	16.807147	168071	
Copper and Its Alloys	Iron	7439-89-6	0.92784	2.4	24000	0.414033	4140	
Copper and Its Alloys	Phosphorus	7723-14-0	0.005799	0.015	150	0.002588	26	
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.011598	0.03	300	0.005175	52	
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.011598	0.03	300	0.005175	52	
Zinc and Its Alloys	Zinc	7440-66-6	0.03866	0.1	1000	0.017251	173	
Sub-Total			38.66	100	1000000	17.25137	172514	
Lead Frame Plating								
Nickel and Its Alloys	Nickel	7440-02-0	1.655088	95.12	951200	0.738555	7386	
Precious Metals	Gold	7440-57-5	0.013572	0.78	7800	0.006056	61	
Precious Metals	Palladium	7440-05-3	0.07134	4.1	41000	0.031834	318	
Sub-Total			1.74	100	1000000	0.776445	7764	
Mold Compound								
Other Inorganic Materials	Fused Silica	60676-86-0	160.99168	88	880000	71.839808	718398	
Other Plastics and Rubber	Carbon Black	1333-86-4	0.548835	0.3	3000	0.244908	2449	
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	1.006198	0.55	5500	0.448999	4490	
Thermoplastics	Epoxy	85954-11-6	20.398378	11.15	111500	9.10243	91024	
Sub-Total			182.945091	100	1000000	81.636145	816361	
Semiconductor Device								
Ceramics / Glass	Doped Silicon	7440-21-3	0.50309	100	1000000	0.224495	2245	
Sub-Total			0.50309	100	1000000	0.224495	2245	
Total			224.09815	·		100	1000000	

## Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

## Important Part Information

T. There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## **Product Content Methodology**

For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

# Important Information/Disclaimer

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Ti may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Il and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials.

Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szg088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.